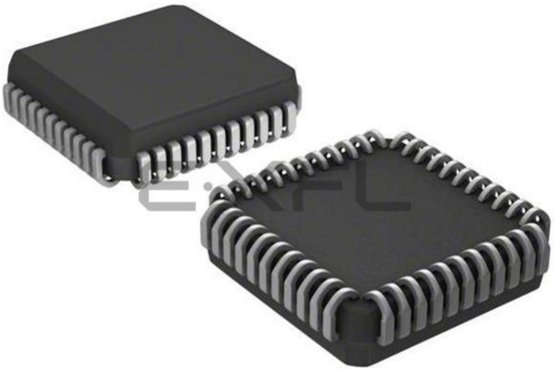


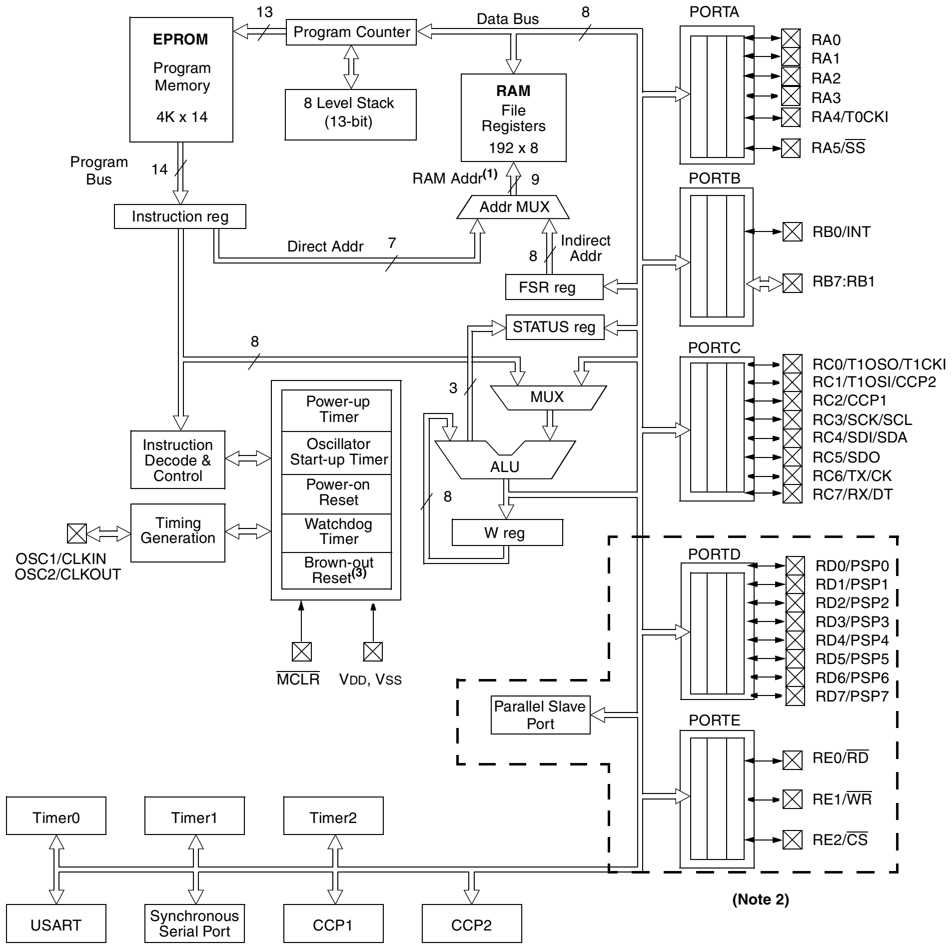
What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	33
Program Memory Size	14KB (8K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	368 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 6V
Data Converters	-
Oscillator Type	External
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	44-LCC (J-Lead)
Supplier Device Package	44-PLCC (16.59x16.59)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lc67t-04-l

FIGURE 3-3: PIC16C63/R63/65/65A/R65 BLOCK DIAGRAM



Note 1: Higher order bits are from the STATUS register.
2: PORTD, PORTE and the Parallel Slave Port are not available on the PIC16C63/R63.
3: Brown-out Reset is not available on the PIC16C65.

TABLE 4-3: SPECIAL FUNCTION REGISTERS FOR THE PIC16C63/R63

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other resets(3)
Bank 0											
00h(1)	INDF	Addressing this location uses contents of FSR to address data memory (not a physical register)								0000 0000	0000 0000
01h	TMR0	Timer0 module’s register								xxxx xxxx	uuuu uuuu
02h(1)	PCL	Program Counter's (PC) Least Significant Byte								0000 0000	0000 0000
03h(1)	STATUS	IRP(4)	RP1(4)	RP0	$\overline{\text{TO}}$	$\overline{\text{PD}}$	Z	DC	C	0001 1xxx	000q quuu
04h(1)	FSR	Indirect data memory address pointer								xxxx xxxx	uuuu uuuu
05h	PORTA	—	—	PORTA Data Latch when written: PORTA pins when read						--xx xxxx	--uu uuuu
06h	PORTB	PORTB Data Latch when written: PORTB pins when read								xxxx xxxx	uuuu uuuu
07h	PORTC	PORTC Data Latch when written: PORTC pins when read								xxxx xxxx	uuuu uuuu
08h	—	Unimplemented								—	—
09h	—	Unimplemented								—	—
0Ah(1,2)	PCLATH	—	—	—	Write Buffer for the upper 5 bits of the Program Counter					---0 0000	---0 0000
0Bh(1)	INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000u
0Ch	PIR1	(5)	(5)	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
0Dh	PIR2	—	—	—	—	—	—	—	CCP2IF	---- ---0	---- ---0
0Eh	TMR1L	Holding register for the Least Significant Byte of the 16-bit TMR1 register								xxxx xxxx	uuuu uuuu
0Fh	TMR1H	Holding register for the Most Significant Byte of the 16-bit TMR1 register								xxxx xxxx	uuuu uuuu
10h	T1CON	—	—	T1CKPS1	T1CKPS0	T1OSCEN	$\overline{\text{T1SYNC}}$	TMR1CS	TMR1ON	--00 0000	--uu uuuu
11h	TMR2	Timer2 module’s register								0000 0000	0000 0000
12h	T2CON	—	TOUTPS3	TOUTPS2	TOUTPS1	TOUTPS0	TMR2ON	T2CKPS1	T2CKPS0	-000 0000	-000 0000
13h	SSPBUF	Synchronous Serial Port Receive Buffer/Transmit Register								xxxx xxxx	uuuu uuuu
14h	SSPCON	WCOL	SSPOV	SSPEN	CKP	SSPM3	SSPM2	SSPM1	SSPM0	0000 0000	0000 0000
15h	CCPR1L	Capture/Compare/PWM1 (LSB)								xxxx xxxx	uuuu uuuu
16h	CCPR1H	Capture/Compare/PWM1 (MSB)								xxxx xxxx	uuuu uuuu
17h	CCP1CON	—	—	CCP1X	CCP1Y	CCP1M3	CCP1M2	CCP1M1	CCP1M0	--00 0000	--00 0000
18h	RCSTA	SPEN	RX9	SREN	CREN	—	FERR	OERR	RX9D	0000 -00x	0000 -00x
19h	TXREG	USART Transmit Data Register								0000 0000	0000 0000
1Ah	RCREG	USART Receive Data Register								0000 0000	0000 0000
1Bh	CCPR2L	Capture/Compare/PWM2 (LSB)								xxxx xxxx	uuuu uuuu
1Ch	CCPR2H	Capture/Compare/PWM2 (MSB)								xxxx xxxx	uuuu uuuu
1Dh	CCP2CON	—	—	CCP2X	CCP2Y	CCP2M3	CCP2M2	CCP2M1	CCP2M0	--00 0000	--00 0000
1Eh-1Fh	—	Unimplemented								—	—

Legend: x = unknown, u = unchanged, q = value depends on condition, - = unimplemented location read as '0'.
Shaded locations are unimplemented, read as ‘0’.

Note 1: These registers can be addressed from either bank.
2: The upper byte of the Program Counter (PC) is not directly accessible. PCLATH is a holding register for the PC whose contents are transferred to the upper byte of the program counter. (PC<12:8>)
3: Other (non power-up) resets include external reset through $\overline{\text{MCLR}}$ and the Watchdog Timer reset.
4: The IRP and RP1 bits are reserved on the PIC16C63/R63, always maintain these bits clear.
5: PIE1<7:6> and PIR1<7:6> are reserved on the PIC16C63/R63, always maintain these bits clear.

4.2.2.4 PIE1 REGISTER

Applicable Devices													
61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67

This register contains the individual enable bits for the peripheral interrupts.

Note: Bit PEIE (INTCON<6>) must be set to enable any peripheral interrupt.

FIGURE 4-12: PIE1 REGISTER FOR PIC16C62/62A/R62 (ADDRESS 8Ch)

RW-0	R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	—	SSPIE	CCP1IE	TMR2IE	TMR1IE
bit7							bit0

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as ‘0’
- n = Value at POR reset

bit 7-6: **Reserved**: Always maintain these bits clear.

bit 5-4: **Unimplemented**: Read as '0'

bit 3: **SSPIE**: Synchronous Serial Port Interrupt Enable bit
1 = Enables the SSP interrupt
0 = Disables the SSP interrupt

bit 2: **CCP1IE**: CCP1 Interrupt Enable bit
1 = Enables the CCP1 interrupt
0 = Disables the CCP1 interrupt

bit 1: **TMR2IE**: TMR2 to PR2 Match Interrupt Enable bit
1 = Enables the TMR2 to PR2 match interrupt
0 = Disables the TMR2 to PR2 match interrupt

bit 0: **TMR1IE**: TMR1 Overflow Interrupt Enable bit
1 = Enables the TMR1 overflow interrupt
0 = Disables the TMR1 overflow interrupt

4.2.2.6 PIE2 REGISTER

Applicable Devices													
61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67

This register contains the CCP2 interrupt enable bit.

FIGURE 4-20: PIE2 REGISTER (ADDRESS 8Dh)

U-0	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0
—	—	—	—	—	—	—	CCP2IE
bit7							bit0

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as ‘0’
- n = Value at POR reset

bit 7-1: **Unimplemented:** Read as '0'

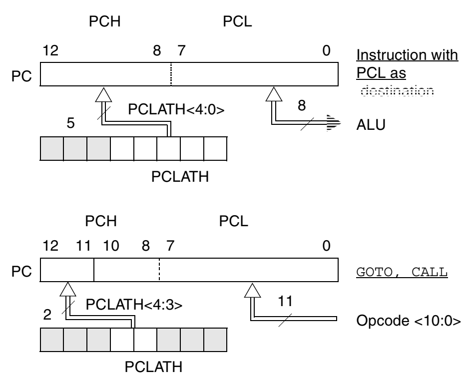
bit 0: **CCP2IE**: CCP2 Interrupt Enable bit
1 = Enables the CCP2 interrupt
0 = Disables the CCP2 interrupt

4.3 PCL and PCLATH

Applicable Devices													
61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67

The program counter (PC) is 13-bits wide. The low byte comes from the PCL register, which is a readable and writable register. The upper bits (PC<12:8>) are not readable, but are indirectly writable through the PCLATH register. On any reset, the upper bits of the PC will be cleared. Figure 4-24 shows the two situations for the loading of the PC. The upper example in the figure shows how the PC is loaded on a write to PCL (PCLATH<4:0> → PCH). The lower example in the figure shows how the PC is loaded during a `CALL` or `GOTO` instruction (PCLATH<4:3> → PCH).

FIGURE 4-24: LOADING OF PC IN DIFFERENT SITUATIONS



4.3.1 COMPUTED GOTO

A computed GOTO is accomplished by adding an offset to the program counter (`ADDWF PCL`). When doing a table read using a computed GOTO method, care should be exercised if the table location crosses a PCL memory boundary (each 256 word block). Refer to the application note *"Implementing a Table Read"* (AN556).

4.3.2 STACK

The PIC16CXX family has an 8 deep x 13-bit wide hardware stack. The stack space is not part of either program or data space and the stack pointer is not readable or writable. The PC is PUSHed onto the stack when a `CALL` instruction is executed or an interrupt causes a branch. The stack is POPed in the event of a `RETURN`, `RETLW` or a `RETFIE` instruction execution. PCLATH is not affected by a PUSH or a POP operation.

The stack operates as a circular buffer. This means that after the stack has been PUSHed eight times, the ninth push overwrites the value that was stored from the first push. The tenth push overwrites the second push (and so on).

Note 1: There are no status bits to indicate stack overflows or stack underflow conditions.

Note 2: There are no instructions mnemonics called PUSH or POP. These are actions that occur from the execution of the `CALL`, `RETURN`, `RETLW`, and `RETFIE` instructions, or the vectoring to an interrupt address

4.4 Program Memory Paging

Applicable Devices													
61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67

PIC16C6X devices are capable of addressing a continuous 8K word block of program memory. The `CALL` and `GOTO` instructions provide only 11 bits of address to allow branching within any 2K program memory page. When doing a `CALL` or `GOTO` instruction the upper two bits of the address are provided by PCLATH<4:3>. When doing a `CALL` or `GOTO` instruction, the user must ensure that the page select bits are programmed so that the desired program memory page is addressed. If a return from a `CALL` instruction (or interrupt) is executed, the entire 13-bit PC is pushed onto the stack. Therefore, manipulation of the PCLATH<4:3> bits are not required for the return instructions (which POPs the address from the stack).

Note: PIC16C6X devices with 4K or less of program memory ignore paging bit PCLATH<4>. The use of PCLATH<4> as a general purpose read/write bit is not recommended since this may affect upward compatibility with future products.

11.0 SYNCHRONOUS SERIAL PORT (SSP) MODULE

11.1 SSP Module Overview

The Synchronous Serial Port (SSP) module is a serial interface useful for communicating with other peripheral or microcontroller devices. These peripheral devices may be Serial EEPROMs, shift registers, display drivers, A/D converters, etc. The SSP module can operate in one of two modes:

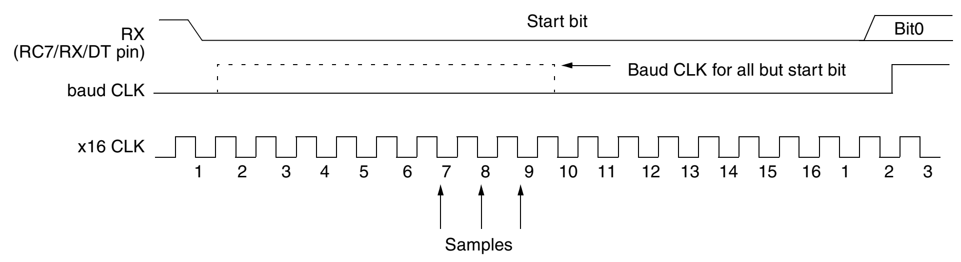
- Serial Peripheral Interface (SPI)
- Inter-Integrated Circuit (I^2C)

The SSP module in I^2C mode works the same in all PIC16C6X devices that have an SSP module. However the SSP Module in SPI mode has differences between the PIC16C66/67 and the other PIC16C6X devices.

The register definitions and operational description of SPI mode has been split into two sections because of the differences between the PIC16C66/67 and the other PIC16C6X devices. The default reset values of both the SPI modules is the same regardless of the device:

Refer to Application Note AN578, *“Use of the SSP Module in the* I^2C *Multi-Master Environment.”*

FIGURE 12-6: RX PIN SAMPLING SCHEME (BRGH = 0 OR = 1) (PIC16C66/67)



12.3 USART Synchronous Master Mode

Applicable Devices													
61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67

In Synchronous Master mode the data is transmitted in a half-duplex manner i.e., transmission and reception do not occur at the same time. When transmitting data the reception is inhibited and vice versa. Synchronous mode is entered by setting bit SYNC (TXSTA<4>). In addition enable bit SPEN (RCSTA<7>) is set in order to configure the RC6 and RC7 I/O pins to CK (clock) and DT (data) lines respectively. The Master mode indicates that the processor transmits the master clock on the CK line. The Master mode is entered by setting bit CSRC (TXSTA<7>).

12.3.1 USART SYNCHRONOUS MASTER TRANSMISSION

The USART transmitter block diagram is shown in Figure 12-7. The heart of the transmitter is the transmit (serial) shift register (TSR). The shift register obtains its data from the read/write transmit buffer register, TXREG. The TXREG register is loaded with data in software. The TSR register is not loaded until the last bit has been transmitted from the previous load. As soon as the last bit is transmitted, the TSR register is loaded with new data from the TXREG register (if available). Once the TXREG register transfers the data to the TSR register (occurs in one Tcycle), the TXREG register is empty and interrupt flag bit TXIF (PIR1<4>) is set. This interrupt can be enabled/disabled by setting/clearing enable bit TXIE (PIE1<4>). Flag bit TXIF will be set regardless of the status of enable bit TXIE and cannot be cleared in software. It will clear only when new data is loaded into the TXREG register. While flag bit TXIF indicates the status of the TXREG register, another bit, TRMT (TXSTA<1>), shows the status of the TSR register. Status bit TRMT is a read only bit which is set when the TSR register is empty. No interrupt logic is tied to this bit, so the user has to poll this bit in order to determine if the TSR register is empty. The TSR register is not mapped in data memory so it is not available to the user.

Transmission is enabled by setting enable bit TXEN (TXSTA<5>). The actual transmission will not occur until the TXREG register has been loaded with data. The first data bit will be shifted out on the next available rising edge of the clock on the CK line. Data out is stable around the falling edge of the synchronous clock (Figure 12-12). The transmission can also be started by first loading the TXREG register and then setting enable bit TXEN (Figure 12-13). This is advantageous when slow baud rates are selected, since the BRG is kept in reset when bits TXEN, CREN, and SREN are clear. Setting enable bit TXEN will start the BRG, creating a shift clock immediately. Normally when transmission is first started, the TSR register is empty, so a transfer to the TXREG register will result in an immediate transfer to TSR resulting in an empty TXREG register. Back-to-back transfers are possible.

Clearing enable bit TXEN, during a transmission, will cause the transmission to be aborted and will reset the transmitter. The DT and CK pins will revert to hi-impedance. If, during a transmission, either bit CREN or bit SREN is set the transmission is aborted and the DT pin reverts to a hi-impedance state (for a reception). The CK pin will remain an output if bit CSRC is set (internal clock). The transmitter logic however, is not reset although it is disconnected from the pins. In order to reset the transmitter, the user has to clear enable bit TXEN. If enable bit SREN is set (to interrupt an on going transmission and receive a single word), then after the single word is received, enable bit SREN will be cleared, and the serial port will revert back to transmitting since enable bit TXEN is still set. The DT line will immediately switch from hi-impedance receive mode to transmit and start driving. To avoid this, enable bit TXEN should be cleared.

In order to select 9-bit transmission, bit TX9 (TXSTA<6>) should be set and the ninth bit should be written to bit TX9D (TXSTA<0>). The ninth bit must be written before writing the 8-bit data to the TXREG register. This is because a data write to the TXREG register can result in an immediate transfer of the data to the TSR register (if the TSR is empty). If the TSR register was empty and the TXREG register was written before writing the “new” TX9D, the “present” value of bit TX9D is loaded.

Steps to follow when setting up a Synchronous Master Transmission:

1. Initialize the SPBRG register for the appropriate baud rate (Section 12.1).
2. Enable the synchronous master serial port by setting bits SYNC, SPEN, and CSRC.
3. If interrupts are desired, then set enable bit TXIE.
4. If 9-bit transmission is desired, then set bit TX9.
5. Enable the transmission by setting enable bit TXEN.
6. If 9-bit transmission is selected, the ninth bit should be loaded in bit TX9D.
7. Start transmission by loading data to the TXREG register.

13.2.3 EXTERNAL CRYSTAL OSCILLATOR CIRCUIT

Either a prepackaged oscillator can be used or a simple oscillator circuit with TTL gates can be built. Prepackaged oscillators provide a wide operating range and better stability. A well-designed crystal oscillator will provide good performance with TTL gates. Two types of crystal oscillator circuits can be used; one with series resonance, or one with parallel resonance.

Figure 13-6 shows implementation of a parallel resonant oscillator circuit. The circuit is designed to use the fundamental frequency of the crystal. The 74AS04 inverter performs the 180-degree phase shift that a parallel oscillator requires. The 4.7 kΩ resistor provides the negative feedback for stability. The 10 kΩ potentiometer biases the 74AS04 in the linear region. This could be used for external oscillator designs.

FIGURE 13-6: EXTERNAL PARALLEL RESONANT CRYSTAL OSCILLATOR CIRCUIT

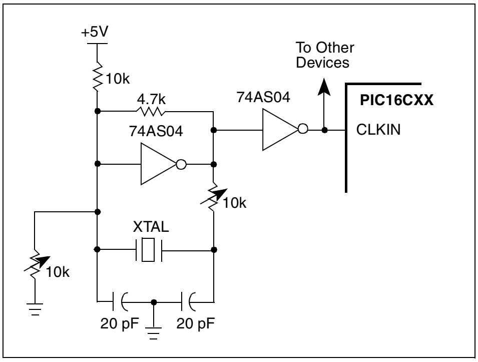
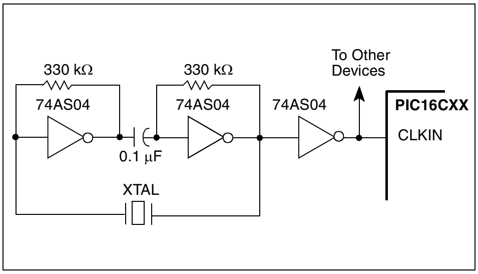


Figure 13-7 shows a series resonant oscillator circuit. This circuit is also designed to use the fundamental frequency of the crystal. The inverter performs a 180-degree phase shift in a series resonant oscillator circuit. The 330 kΩ resistors provide the negative feedback to bias the inverters in their linear region.

FIGURE 13-7: EXTERNAL SERIES RESONANT CRYSTAL OSCILLATOR CIRCUIT



13.2.4 RC OSCILLATOR

For timing insensitive applications the RC device option offers additional cost savings. The RC oscillator frequency is a function of the supply voltage, the resistor (Rext) and capacitor (Cext) values, and the operating temperature. In addition to this, the oscillator frequency will vary from unit to unit due to normal process parameter variation. Furthermore, the difference in lead frame capacitance between package types will also affect the oscillation frequency, especially for low Cext values. The user also needs to take into account variation due to tolerance of external R and C components used. Figure 13-8 shows how the RC combination is connected to the PIC16CXX. For Rext values below 2.2 kΩ, the oscillator operation may become unstable or stop completely. For very high Rext values (e.g. 1 MΩ), the oscillator becomes sensitive to noise, humidity and leakage. Thus, we recommend keeping Rext between 3 kΩ and 100 kΩ.

Although the oscillator will operate with no external capacitor (Cext = 0 pF), we recommend using values above 20 pF for noise and stability reasons. With no or small external capacitance, the oscillation frequency can vary dramatically due to changes in external capacitances, such as PCB trace capacitance or package lead frame capacitance.

See characterization data for desired device for RC frequency variation from part to part due to normal process variation. The variation is larger for larger R (since leakage current variation will affect RC frequency more for large R) and for smaller C (since variation of input capacitance will affect RC frequency more).

See characterization data for desired device for variation of oscillator frequency due to VDD for given Rext/Cext values as well as frequency variation due to operating temperature for given R, C, and VDD values.

The oscillator frequency, divided by 4, is available on the OSC2/CLKOUT pin, and can be used for test purposes or to synchronize other logic (see Figure 3-5 for waveform).

FIGURE 13-8: RC OSCILLATOR MODE

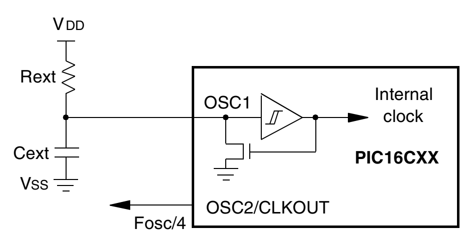


FIGURE 13-17: INTERRUPT LOGIC FOR PIC16C61

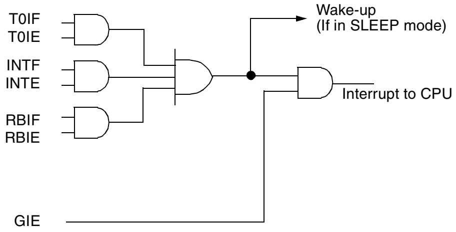
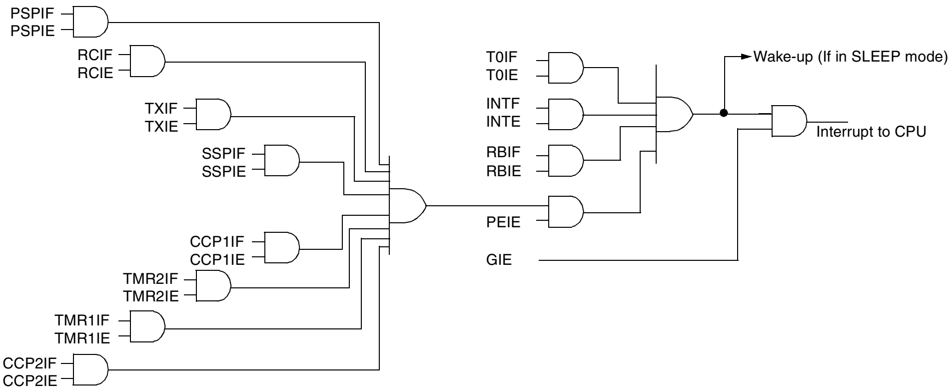


FIGURE 13-18: INTERRUPT LOGIC FOR PIC16C6X



The following table shows which devices have which interrupts.

Device	T0IF	INTF	RBIF	PSPIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	CCP2IF
PIC16C62	Yes	Yes	Yes	-	-	-	Yes	Yes	Yes	Yes	-
PIC16C62A	Yes	Yes	Yes	-	-	-	Yes	Yes	Yes	Yes	-
PIC16CR62	Yes	Yes	Yes	-	-	-	Yes	Yes	Yes	Yes	-
PIC16C63	Yes	Yes	Yes	-	Yes	Yes	Yes	Yes	Yes	Yes	Yes
PIC16CR63	Yes	Yes	Yes	-	Yes	Yes	Yes	Yes	Yes	Yes	Yes
PIC16C64	Yes	Yes	Yes	Yes	-	-	Yes	Yes	Yes	Yes	-
PIC16C64A	Yes	Yes	Yes	Yes	-	-	Yes	Yes	Yes	Yes	-
PIC16C64	Yes	Yes	Yes	Yes	-	-	Yes	Yes	Yes	Yes	-
PIC16C65	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes
PIC16C65A	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes
PIC16CR65	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes
PIC16C66	Yes	Yes	Yes	-	Yes	Yes	Yes	Yes	Yes	Yes	Yes
PIC16C67	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes

Applicable Devices	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67

15.0 ELECTRICAL CHARACTERISTICS FOR PIC16C61

Absolute Maximum Ratings †

Ambient temperature under bias	-55°C to +125°C
Storage temperature	-65°C to +150°C
Voltage on any pin with respect to VSS (except VDD, $\overline{\text{MCLR}}$, and RA4)	-0.3V to (VDD + 0.3V)
Voltage on VDD with respect to VSS	-0.3V to +7.5V
Voltage on $\overline{\text{MCLR}}$ with respect to VSS (Note 2)	0V to +14V
Voltage on RA4 pin with respect to Vss	0V to +14V
Total power dissipation (Note 1)	800 mW
Maximum current out of VSS pin	150 mA
Maximum current into VDD pin	100 mA
Input clamp current, IIK (VI < 0 or VI > VDD)	± 20 mA
Output clamp current, IOK (VO < 0 or VO > VDD)	± 20 mA
Maximum output current sunk by any I/O pin	25 mA
Maximum output current sourced by any I/O pin	20 mA
Maximum current sunk by PORTA	80 mA
Maximum current sourced by PORTA	50 mA
Maximum current sunk by PORTB	150 mA
Maximum current sourced by PORTB	100 mA

Note 1: Power dissipation is calculated as follows: Pdis = VDD x {IDD - Σ IOH} + Σ {(VDD-VOH) x IOH} + Σ(VOl x IOL)

Note 2: Voltage spikes below VSS at the $\overline{\text{MCLR}}$ pin, inducing currents greater than 80 mA, may cause latch-up. Thus, a series resistor of 50-100Ω should be used when applying a “low” level to the $\overline{\text{MCLR}}$ pin rather than pulling this pin directly to VSS.

† NOTICE: Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

TABLE 15-1: CROSS REFERENCE OF DEVICE SPECS FOR OSCILLATOR CONFIGURATIONS AND FREQUENCIES OF OPERATION (COMMERCIAL DEVICES)

OSC	PIC16C61-04	PIC16C61-20	PIC16LC61-04	JW Devices
RC	VDD: 4.0V to 6.0V IDD: 3.3 mA max. at 5.5V IPD: 14 µA max. at 4V Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 1.8 mA typ. at 5.5V IPD: 1.0 µA typ. at 4V Freq: 4 MHz max.	VDD: 3.0V to 6.0V IDD: 1.4 mA typ. at 3.0V IPD: 0.6 µA typ. at 3V Freq: 4 MHz max.	VDD: 4.0V to 6.0V IDD: 3.3 mA max. at 5.5V IPD: 14 µA max. at 4V Freq: 4 MHz max.
XT	VDD: 4.0V to 6.0V IDD: 3.3 mA max. at 5.5V IPD: 14 µA max. at 4V Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 1.8 mA typ. at 5.5V IPD: 1.0 µA typ. at 4V Freq: 4 MHz max.	VDD: 3.0V to 6.0V IDD: 1.4 mA typ. at 3.0V IPD: 0.6 µA typ. at 3V Freq: 4 MHz max.	VDD: 4.0V to 6.0V IDD: 3.3 mA max. at 5.5V IPD: 14 µA max. at 4V Freq: 4 MHz max.
HS	VDD: 4.5V to 5.5V IDD: 13.5 mA typ. at 5.5V IPD: 1.0 µA typ. at 4.5V Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 30 mA max. at 5.5V IPD: 1.0 µA typ. at 4.5V Freq: 20 MHz max.	Not recommended for use in HS mode	VDD: 4.5V to 5.5V IDD: 30 mA max. at 5.5V IPD: 1.0 µA typ. at 4.5V Freq: 20 MHz max.
LP	VDD: 4.0V to 6.0V IDD: 15 µA typ. at 32 kHz, 4.0V IPD: 0.6 µA typ. at 4.0V Freq: 200 kHz max.	Not recommended for use in LP mode	VDD: 3.0V to 6.0V IDD: 32 µA max. at 32 kHz, 3.0V IPD: 9 µA max. at 3.0V Freq: 200 kHz max.	VDD: 3.0V to 6.0V IDD: 32 µA max. at 32 kHz, 3.0V IPD: 9 µA max. at 3.0V Freq: 200 kHz max.

The shaded sections indicate oscillator selections which are tested for functionality, but not for MIN/MAX specifications. It is recommended that the user select the device type that ensures the specifications required.

Applicable Devices	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67

15.3 DC Characteristics: PIC16C61-04 (Commercial, Industrial, Extended)
PIC16C61-20 (Commercial, Industrial, Extended)
PIC16LC61-04 (Commercial, Industrial)

DC CHARACTERISTICS	**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +125°C for extended, -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial Operating voltage VDD range as described in DC spec Section 15.1 and Section 15.2.

Param No.	Characteristic	Sym	Min	Typ†	Max	Units	Conditions
	Input Low Voltage						
	I/O ports	VIL					
D030	with TTL buffer		Vss	-	0.15VDD	V	For entire VDD range
D030A			VSS	-	0.8V	V	4.5V ≤ VDD ≤ 5.5V
D031	with Schmitt Trigger buffer		Vss	-	0.2VDD	V	
D032	$\overline{\text{MCLR}}$, OSC1 (in RC mode)		Vss	-	0.2VDD	V	
D033	OSC1 (in XT, HS and LP)		Vss	-	0.3VDD	V	Note1
	Input High Voltage						
	I/O ports	VIH		-			
D040	with TTL buffer		2.0	-	VDD	V	4.5V ≤ VDD ≤ 5.5V
D040A			0.25VDD + 0.8V	-	VDD	V	For entire VDD range
D041	with Schmitt Trigger buffer		0.85VDD	-	VDD	V	For entire VDD range
D042	$\overline{\text{MCLR}}$		0.85VDD	-	VDD	V	
D042A	OSC1 (XT, HS and LP)		0.7VDD	-	VDD	V	Note1
D043	OSC1 (in RC mode)		0.9VDD	-	VDD	V	
D070	PORTB weak pull-up current	IPURB	50	250	† 400	μA	VDD = 5V, VPIN = VSS
	Input Leakage Current (Notes 2, 3)						
D060	I/O ports	IIL	-	-	±1	μA	Vss ≤ VPIN ≤ VDD, Pin at hi-impedance
D061	$\overline{\text{MCLR}}$, RA4/T0CKI		-	-	±5	μA	Vss ≤ VPIN ≤ VDD
D063	OSC1		-	-	±5	μA	Vss ≤ VPIN ≤ VDD, XT, HS and LP osc configuration
	Output Low Voltage						
D080	I/O ports	VOL	-	-	0.6	V	IOL = 8.5 mA, VDD = 4.5V, -40°C to +85°C
D080A			-	-	0.6	V	IOL = 7.0 mA, VDD = 4.5V, -40°C to +125°C
D083	OSC2/CLKOUT (RC osc config)		-	-	0.6	V	IOL = 1.6 mA, VDD = 4.5V, -40°C to +85°C
D083A			-	-	0.6	V	IOL = 1.2 mA, VDD = 4.5V, -40°C to +125°C

* The parameters are characterized but not tested.

† Data in “Typ” column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

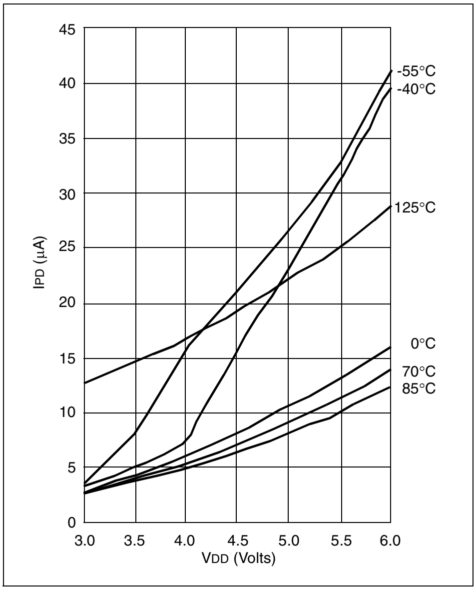
Note 1: In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C6X be driven with external clock in RC mode.

2: The leakage current on the $\overline{\text{MCLR}}$/VPP pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

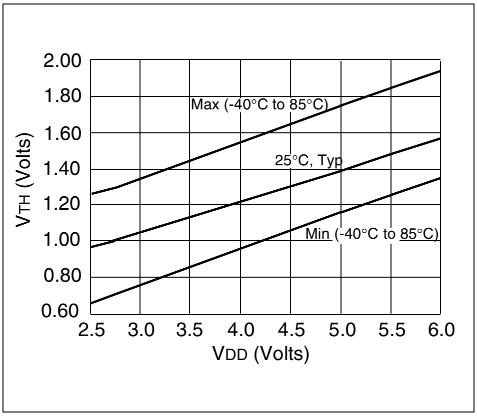
Applicable Devices	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67

FIGURE 16-8: MAXIMUM IPD VS. VDD WATCHDOG ENABLED*



*IPD, with Watchdog Timer enabled, has two components: The leakage current which increases with higher temperature and the operating current of the Watchdog Timer logic which increases with lower temperature. At -40°C, the latter dominates explaining the apparently anomalous behavior.

FIGURE 16-9: VTH (INPUT THRESHOLD VOLTAGE) OF I/O PINS VS. VDD



Data based on matrix samples. See first page of this section for details.

Applicable Devices	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67

FIGURE 16-14: MAXIMUM IDD VS. FREQUENCY (EXTERNAL CLOCK, -55° TO +125°C)

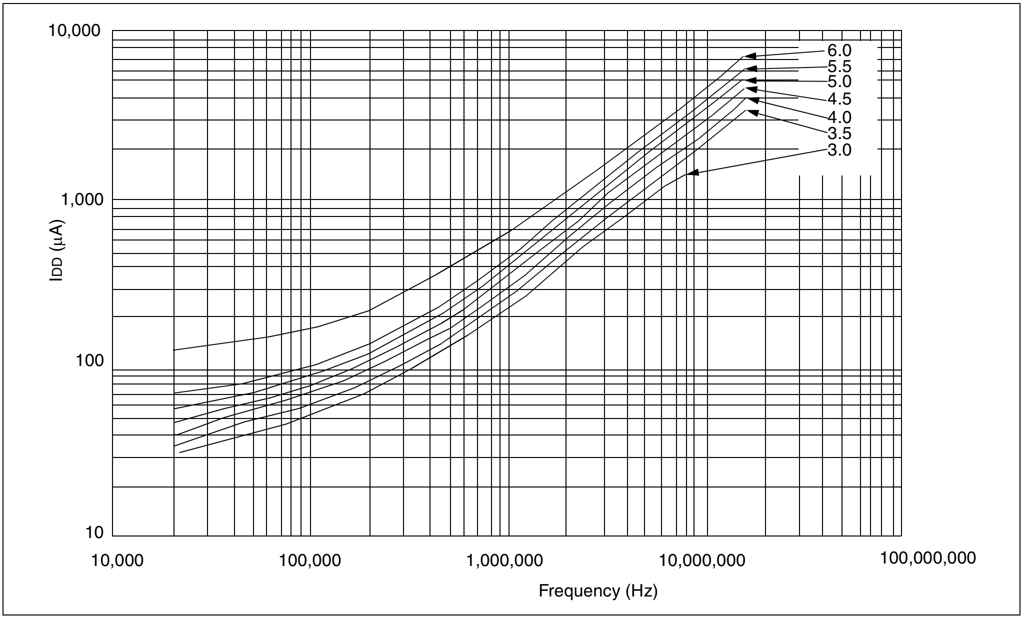


FIGURE 16-15: WDT TIMER TIME-OUT PERIOD VS. VDD

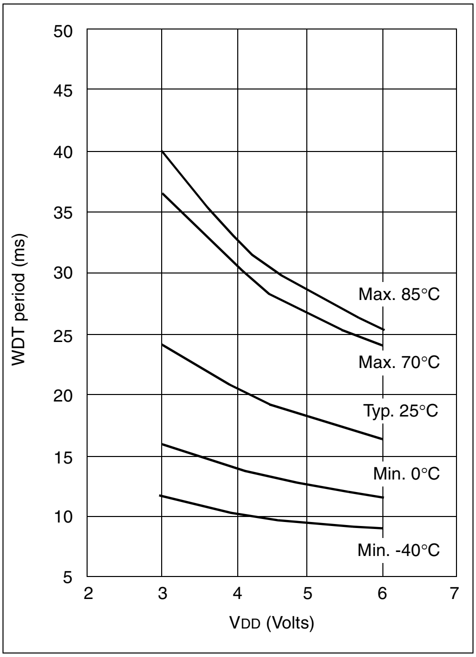
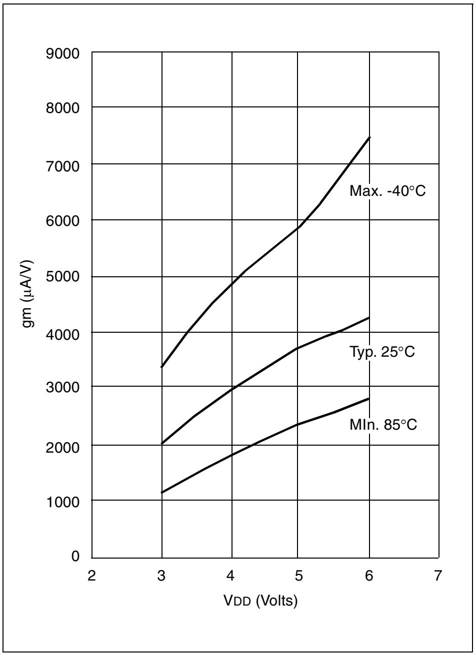


FIGURE 16-16: TRANSCONDUCTANCE (gm) OF HS OSCILLATOR VS. VDD



Data based on matrix samples. See first page of this section for details.

18.0 ELECTRICAL CHARACTERISTICS FOR PIC16C62A/R62/64A/R64

Absolute Maximum Ratings †

Ambient temperature under bias	-55°C to +125°C
Storage temperature	-65°C to +150°C
Voltage on any pin with respect to VSS (except VDD, $\overline{\text{MCLR}}$, and RA4)	-0.3V to (VDD + 0.3V)
Voltage on VDD with respect to VSS	-0.3V to +7.5V
Voltage on $\overline{\text{MCLR}}$ with respect to VSS (Note 2)	0V to +14V
Voltage on RA4 with respect to Vss	0V to +14V
Total power dissipation (Note 1)	1.0W
Maximum current out of VSS pin	300 mA
Maximum current into VDD pin	250 mA
Input clamp current, IIK (VI < 0 or VI > VDD)	±20 mA
Output clamp current, IOK (VO < 0 or VO > VDD)	±20 mA
Maximum output current sunk by any I/O pin	25 mA
Maximum output current sourced by any I/O pin	25 mA
Maximum current sunk by PORTA, PORTB, and PORTE (combined)	200 mA
Maximum current sourced by PORTA, PORTB, and PORTE (combined)	200 mA
Maximum current sunk by PORTC and PORTD (combined)	200 mA
Maximum current sourced by PORTC and PORTD (combined)	200 mA

Note 1: Power dissipation is calculated as follows: Pdis = VDD x {IDD - ∑ IOH} + ∑ {(VDD-VOH) x IOH} + ∑(VOl x IOL)

Note 2: Voltage spikes below VSS at the $\overline{\text{MCLR}}$ pin, inducing currents greater than 80 mA, may cause latch-up. Thus, a series resistor of 50-100Ω should be used when applying a "low" level to the $\overline{\text{MCLR}}$ pin rather than pulling this pin directly to VSS.

† NOTICE: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

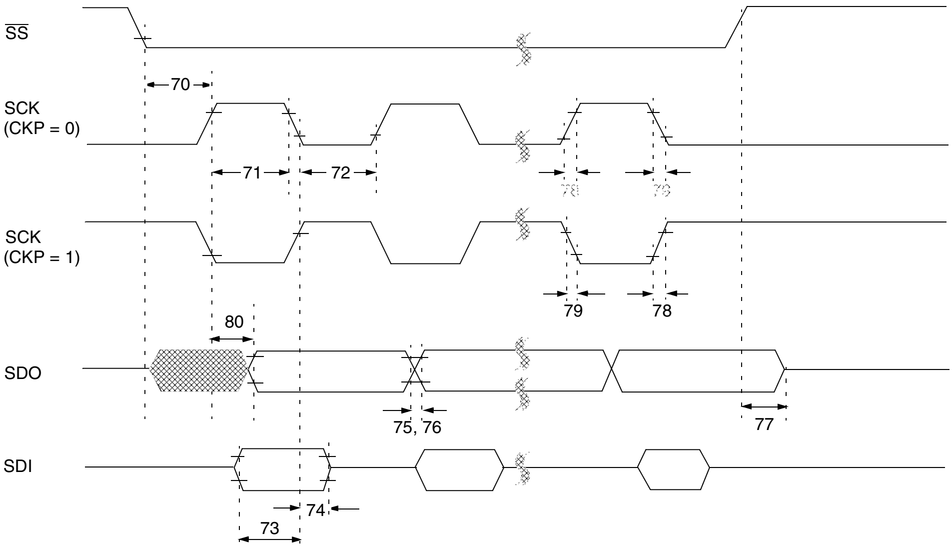
TABLE 18-1: CROSS REFERENCE OF DEVICE SPECS FOR OSCILLATOR CONFIGURATIONS AND FREQUENCIES OF OPERATION (COMMERCIAL DEVICES)

OSC	PIC16C62A-04 PIC16CR62-04 PIC16C64A-04 PIC16CR64-04	PIC16C62A-10 PIC16CR62-10 PIC16C64A-10 PIC16CR64-10	PIC16C62A-20 PIC16CR62-20 PIC16C64A-20 PIC16CR64-20	PIC16LC62A-04 PIC16LCR62-04 PIC16LC64A-04 PIC16LCR64-04	JW Devices
RC	VDD: 4.0V to 6.0V IDD: 5 mA max. at 5.5V IPD: 16 µA max. at 4V Freq:4 MHz max.	VDD: 4.5V to 5.5V IDD: 2.0 mA typ. at 5.5V IPD: 1.5 µA typ. at 4V Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 2.0 mA typ. at 5.5V IPD: 1.5 µA typ. at 4V Freq: 4 MHz max.	VDD: 2.5V to 6.0V IDD: 3.8 mA max. at 3.0V IPD: 5 µA max. at 3V Freq: 4 MHz max.	VDD: 4.0V to 6.0V IDD: 5 mA max. at 5.5V IPD: 16 µA max. at 4V Freq:4 MHz max.
XT	VDD: 4.0V to 6.0V IDD: 5 mA max. at 5.5V IPD: 16 µA max. at 4V Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 2.0 mA typ. at 5.5V IPD: 1.5 µA typ. at 4V Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 2.0 mA typ. at 5.5V IPD: 1.5 µA typ. at 4V Freq: 4 MHz max.	VDD: 2.5V to 6.0V IDD: 3.8 mA max. at 3.0V IPD: 5 µA max. at 3.0V Freq: 4 MHz max.	VDD: 4.0V to 6.0V IDD: 5 mA max. at 5.5V IPD: 16 µA max. at 4V Freq: 4 MHz max.
HS	VDD: 4.5V to 5.5V IDD: 13.5 mA typ. at 5.5V IPD: 1.5 µA typ. at 4.5V Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 10 mA max. at 5.5V IPD: 1.5 µA typ. at 4.5V Freq: 10 MHz max.	VDD: 4.5V to 5.5V IDD: 20 mA max. at 5.5V IPD: 1.5 µA typ. at 4.5V Freq: 20 MHz max.	Not recommended for use in HS mode	VDD: 4.5V to 5.5V IDD: 20 mA max. at 5.5V IPD: 1.5 µA typ. at 4.5V Freq: 20 MHz max.
LP	VDD: 4.0V to 6.0V IDD: 52.5 µA typ. at 32 kHz, 4.0V IPD: 0.9 µA typ. at 4.0V Freq: 200 kHz max.	Not recommended for use in LP mode	Not recommended for use in LP mode	VDD: 2.5V to 6.0V IDD: 48 µA max. at 32 kHz, 3.0V IPD: 5 µA max. at 3.0V Freq: 200 kHz max.	VDD: 2.5V to 6.0V IDD: 48 µA max. at 32 kHz, 3.0V IPD: 5 µA max. at 3.0V Freq: 200 kHz max.

The shaded sections indicate oscillator selections which are tested for functionality, but not for MIN/MAX specifications. It is recommended that the user select the device type that ensures the specifications required.

Applicable Devices	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67

FIGURE 18-9: SPI MODE TIMING



Note: Refer to Figure 18-1 for load conditions

TABLE 18-8: SPI MODE REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
70*	TssL2scH, TssL2scL	$\overline{\text{SS}}$↓ to SCK↓ or SCK↑ input	TCY	—	—	ns	
71*	TscH	SCK input high time (slave mode)	TCY + 20	—	—	ns	
72*	TscL	SCK input low time (slave mode)	TCY + 20	—	—	ns	
73*	TdiV2scH, TdiV2scL	Setup time of SDI data input to SCK edge	50	—	—	ns	
74*	TscH2diL, TscL2diL	Hold time of SDI data input to SCK edge	50	—	—	ns	
75*	TdoR	SDO data output rise time	—	10	25	ns	
76*	TdoF	SDO data output fall time	—	10	25	ns	
77*	TssH2doZ	$\overline{\text{SS}}$↑ to SDO output hi-impedance	10	—	50	ns	
78*	TscR	SCK output rise time (master mode)	—	10	25	ns	
79*	TscF	SCK output fall time (master mode)	—	10	25	ns	
80*	TscH2doV, TscL2doV	SDO data output valid after SCK edge	—	—	50	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Applicable Devices	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67

FIGURE 22-9: SPI MASTER MODE TIMING (CKE = 0)

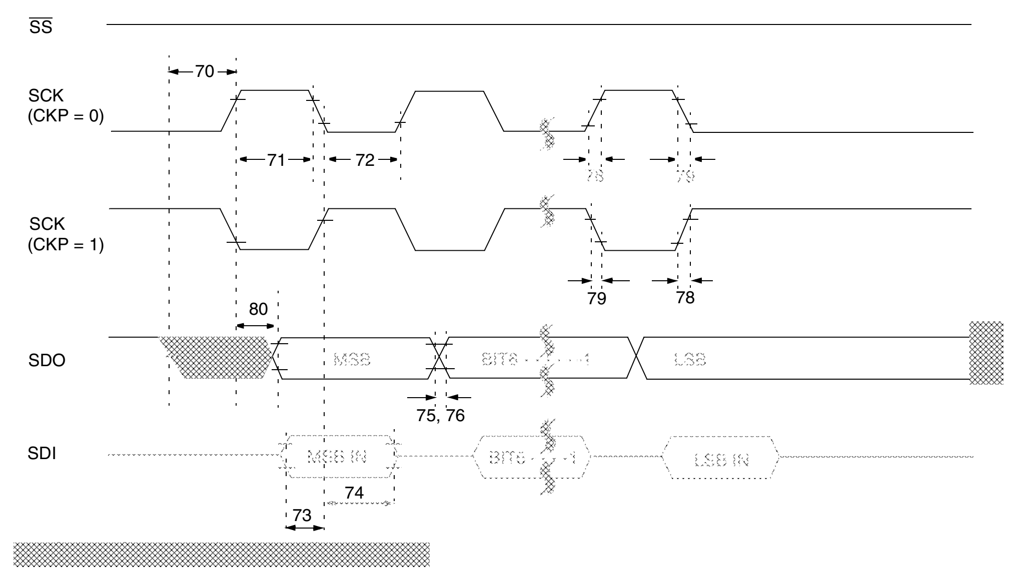
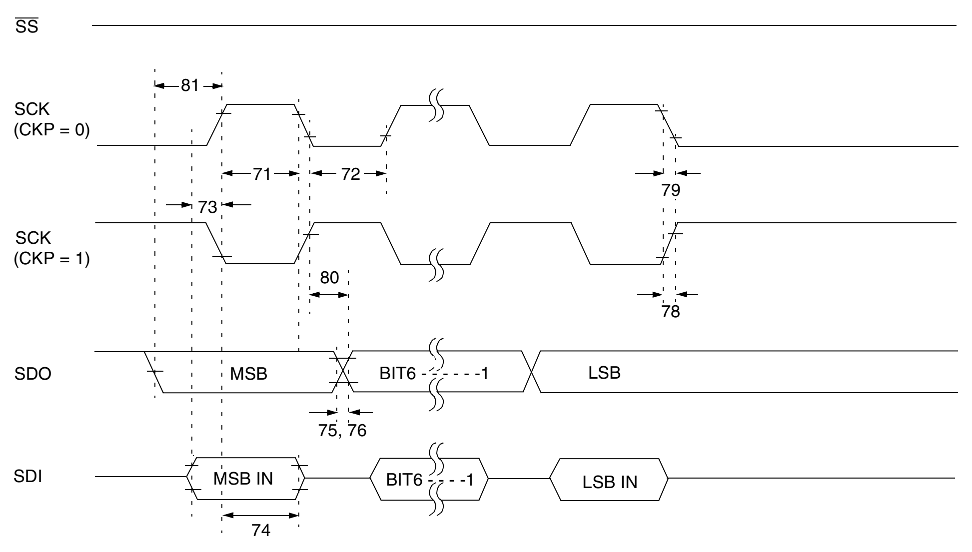


FIGURE 22-10: SPI MASTER MODE TIMING (CKE = 1)



Refer to Figure 22-1 for load conditions.

Applicable Devices	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67

FIGURE 22-15: USART SYNCHRONOUS TRANSMISSION (MASTER/SLAVE) TIMING

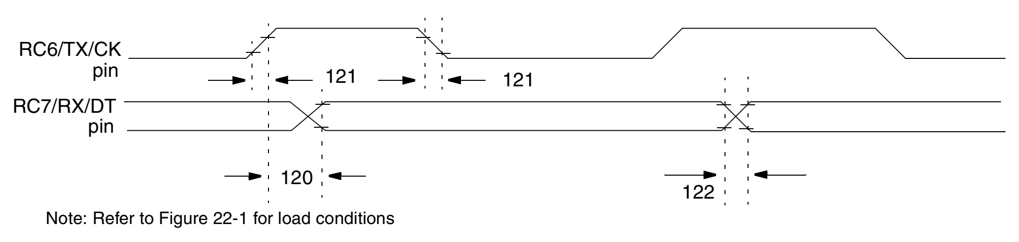


TABLE 22-11: USART SYNCHRONOUS TRANSMISSION REQUIREMENTS

Parameter No.	Sym	Characteristic		Min	Typ†	Max	Units	Conditions
120*	TckH2dtV	SYNC XMIT (MASTER & SLAVE) Clock high to data out valid	PIC16**C**66/67	—	—	80	ns	
			PIC16**LC**66/67	—	—	100	ns	
121*	Tckrf	Clock out rise time and fall time (Master Mode)	PIC16**C**66/67	—	—	45	ns	
			PIC16**LC**66/67	—	—	50	ns	
122*	Tdtrf	Data out rise time and fall time	PIC16**C**66/67	—	—	45	ns	
			PIC16**LC**66/67	—	—	50	ns	

* These parameters are characterized but not tested.

†: Data in “Typ” column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 22-16: USART SYNCHRONOUS RECEIVE (MASTER/SLAVE) TIMING

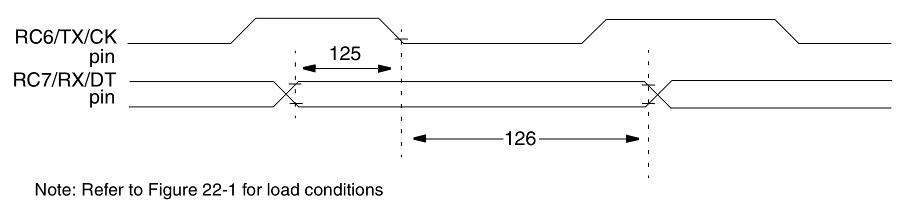


TABLE 22-12: USART SYNCHRONOUS RECEIVE REQUIREMENTS

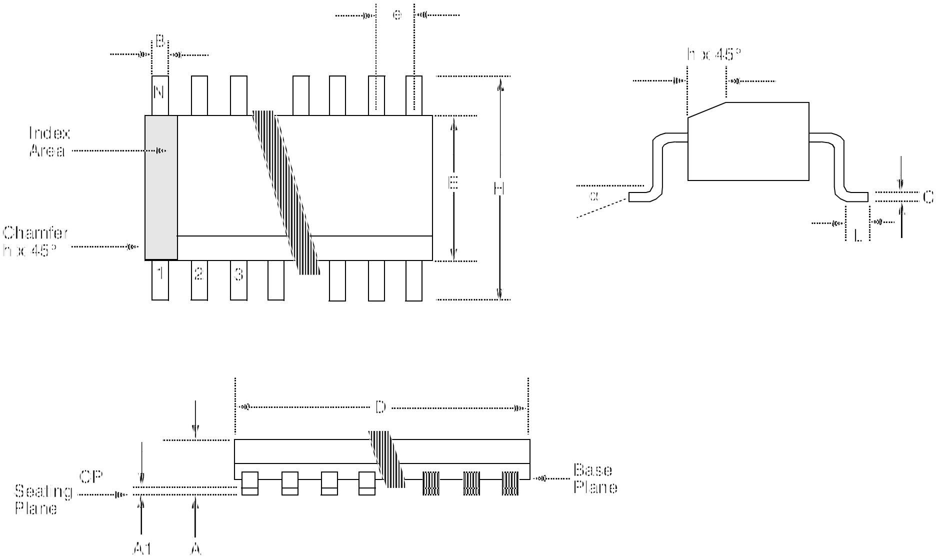
Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
125*	TdtV2ckL	SYNC RCV (MASTER & SLAVE) Data setup before CK ↓ (DT setup time)	15	—	—	ns	
126*	TckL2dtl	Data hold after CK ↓ (DT hold time)	15	—	—	ns	

* These parameters are characterized but not tested.

†: Data in “Typ” column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

24.4 18-Lead Plastic Surface Mount (SOIC - Wide, 300 mil Body) (SO)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Package Group: Plastic SOIC (SO)						
	Millimeters			Inches		
Symbol	Min	Max	Notes	Min	Max	Notes
α	0°	8°		0°	8°	
A	2.362	2.642		0.093	0.104	
A1	0.101	0.300		0.004	0.012	
B	0.355	0.483		0.014	0.019	
C	0.241	0.318		0.009	0.013	
D	11.353	11.735		0.447	0.462	
E	7.416	7.595		0.292	0.299	
e	1.270	1.270	**Reference**	0.050	0.050	**Reference**
H	10.007	10.643		0.394	0.419	
h	0.381	0.762		0.015	0.030	
L	0.406	1.143		0.016	0.045	
N	18	18		18	18	
CP	–	0.102		–	0.004	